

Chip Bead For EMI Suppression

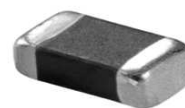
CIB/CIM21 Series (2012/ EIA 0805)

APPLICATION

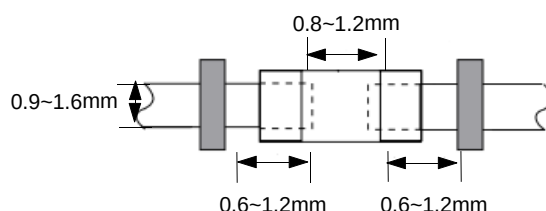
High frequency EMI prevention application to computers, printers, VCRs, TVs and mobile phones.

FEATURES

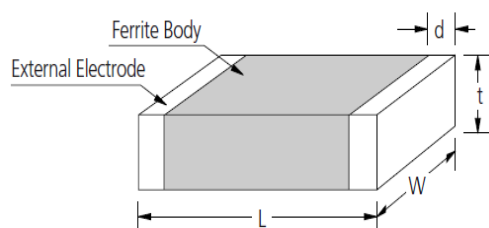
- Perfect shape for automatic mounting, with no directionality.
- Excellent solderability and high heat resistance for either flow or reflow soldering
- Monolithic inorganic material construction for high reliability
- Closed magnetic circuit configuration avoids crosstalk and is suitable for high density PCBs.



RECOMMENDED LAND PATTERN



DIMENSION



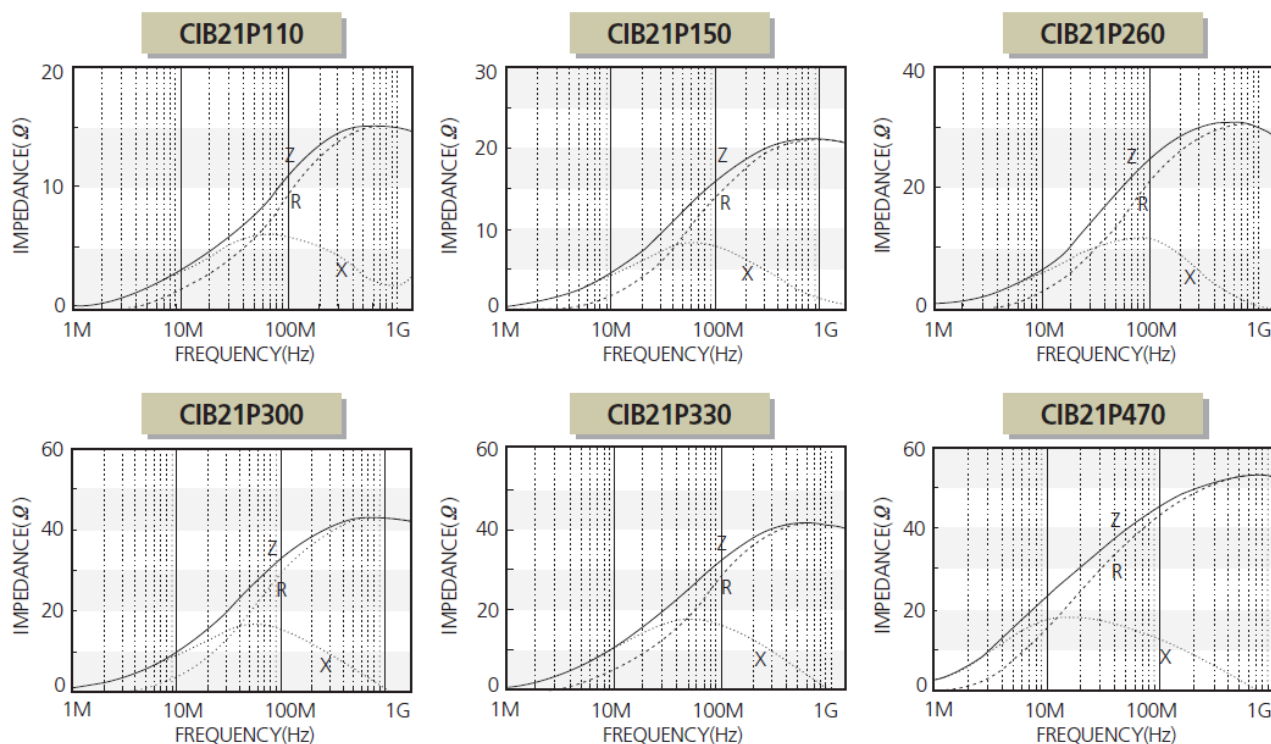
Type	Dimension [mm]			
	L	W	t	d
21	2.0±0.2	1.25±0.2	0.9±0.2	0.5+0.2 -0.3

DESCRIPTION

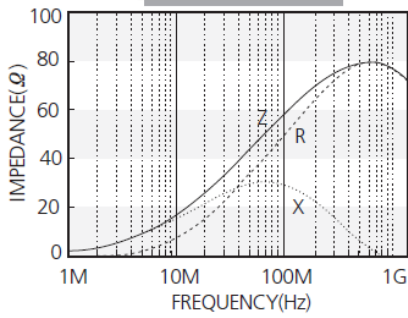
Part no.	Thickness (mm)	Impedance (Ω)±25%@100MHz	DC Resistance (Ω) Max.	Rated Current (mA) Max.
CIB21P110	0.9±0.2	11	0.01	2000
CIB21P150	0.9±0.2	15	0.01	2000
CIB21P260	0.9±0.2	26	0.01	2000
CIB21P300	0.9±0.2	30	0.05	2000
CIB21P330	0.9±0.2	33	0.05	1500
CIB21P470	0.9±0.2	47	0.05	1500
CIM21U600	0.9±0.2	60	0.08	900
CIM21U800	0.9±0.2	80	0.10	900
CIM21U101	0.9±0.2	100	0.10	800
CIM21U121	0.9±0.2	120	0.10	800
CIM21U151	0.9±0.2	150	0.15	600
CIM21U241	0.9±0.2	240	0.15	600
CIM21U301	0.9±0.2	300	0.15	500
CIM21U471	0.9±0.2	470	0.30	500
CIM21U601	0.9±0.2	600	0.30	500
CIM21U102	0.9±0.2	1000(at 70MHz)	0.40	500
CIM21U202	0.9±0.2	2000(at 70MHz)	0.70	300

Part no.	Thickness (mm)	Impedance (Ω) $\pm 25\%$ @100MHz	DC Resistance (Ω) Max.	Rated Current (mA) Max.
CIB21J260	0.9 $\pm$ 0.2	26	0.05	2000
CIB21J300	0.9 $\pm$ 0.2	30	0.05	2000
CIB21J400	0.9 $\pm$ 0.2	40	0.05	2000
CIM21J600	0.9 $\pm$ 0.2	60	0.08	900
CIM21J800	0.9 $\pm$ 0.2	80	0.08	1000
CIM21J121	0.9 $\pm$ 0.2	120	0.15	800
CIM21J151	0.9 $\pm$ 0.2	150	0.15	500
CIM21J221	0.9 $\pm$ 0.2	220	0.20	500
CIM21J241	0.9 $\pm$ 0.2	240	0.20	500
CIM21J301	0.9 $\pm$ 0.2	300	0.20	500
CIM21J471	0.9 $\pm$ 0.2	470	0.25	500
CIM21J601	0.9 $\pm$ 0.2	600	0.25	500
CIM21J751	0.9 $\pm$ 0.2	750	0.35	400
CIM21J102	0.9 $\pm$ 0.2	1000	0.35	500
CIM21J152	0.9 $\pm$ 0.2	1500(at 70MHz)	0.45	500
CIM21J182	0.9 $\pm$ 0.2	1800(at 70MHz)	0.45	500
CIM21J202	0.9 $\pm$ 0.2	2000(at 70MHz)	0.50	500
CIM21J222	0.9 $\pm$ 0.2	2200(at 70MHz)	0.70	300
CIM21J252	0.9 $\pm$ 0.2	2500(at 50MHz)	0.70	300
CIM21K152	0.9 $\pm$ 0.2	1500	0.45	300
CIM21K252	0.9 $\pm$ 0.2	2500	0.80	250
CIM21N560	0.9 $\pm$ 0.2	56	0.20	600
CIM21N700	0.9 $\pm$ 0.2	70	0.20	600
CIM21N121	0.9 $\pm$ 0.2	120	0.25	500
CIM21N241	0.9 $\pm$ 0.2	240	0.30	400

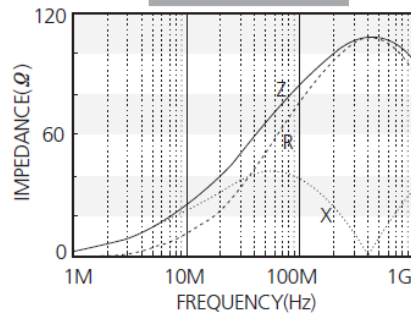
CHARACTERISTIC DATA



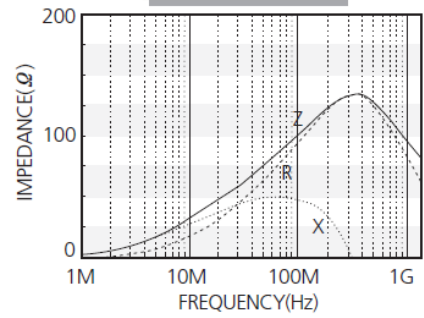
CIM21U600



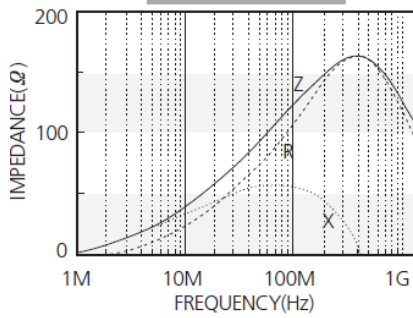
CIM21U800



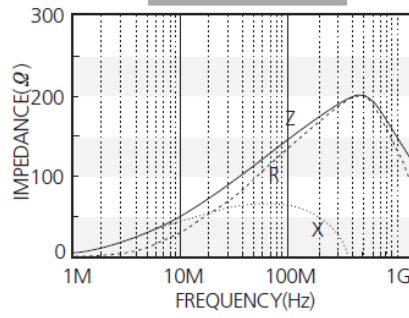
CIM21U101



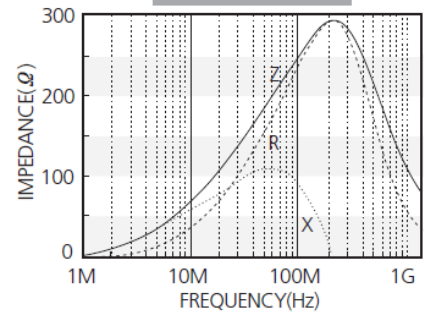
CIM21U121



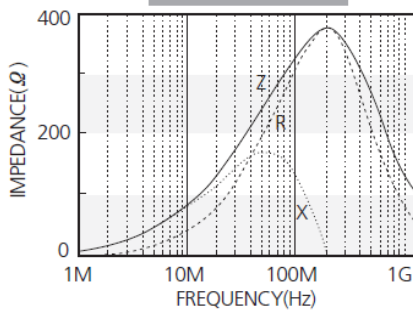
CIM21U151



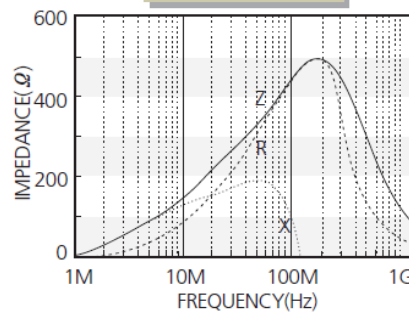
CIM21U241



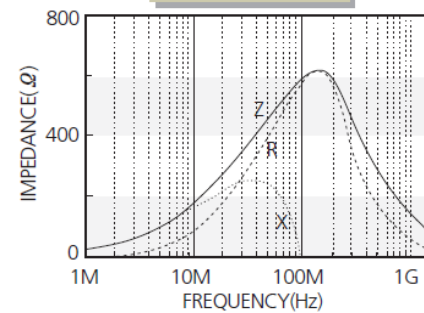
CIM21U301



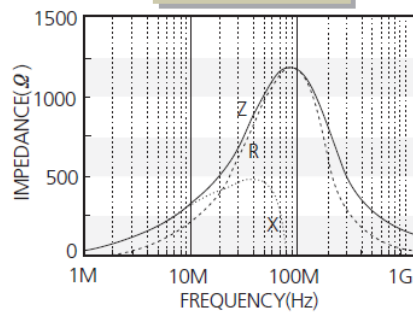
CIM21U471



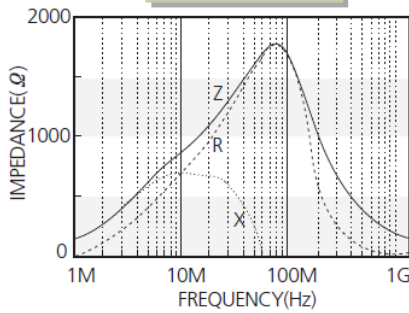
CIM21U601



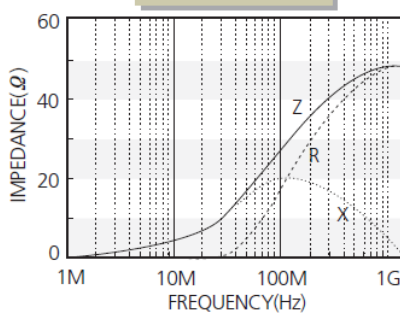
CIM21U102



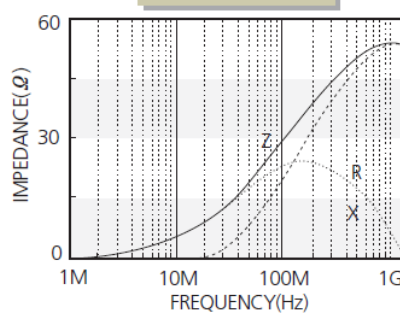
CIM21U202



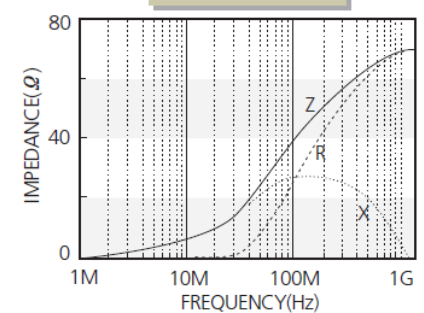
CIB21J260

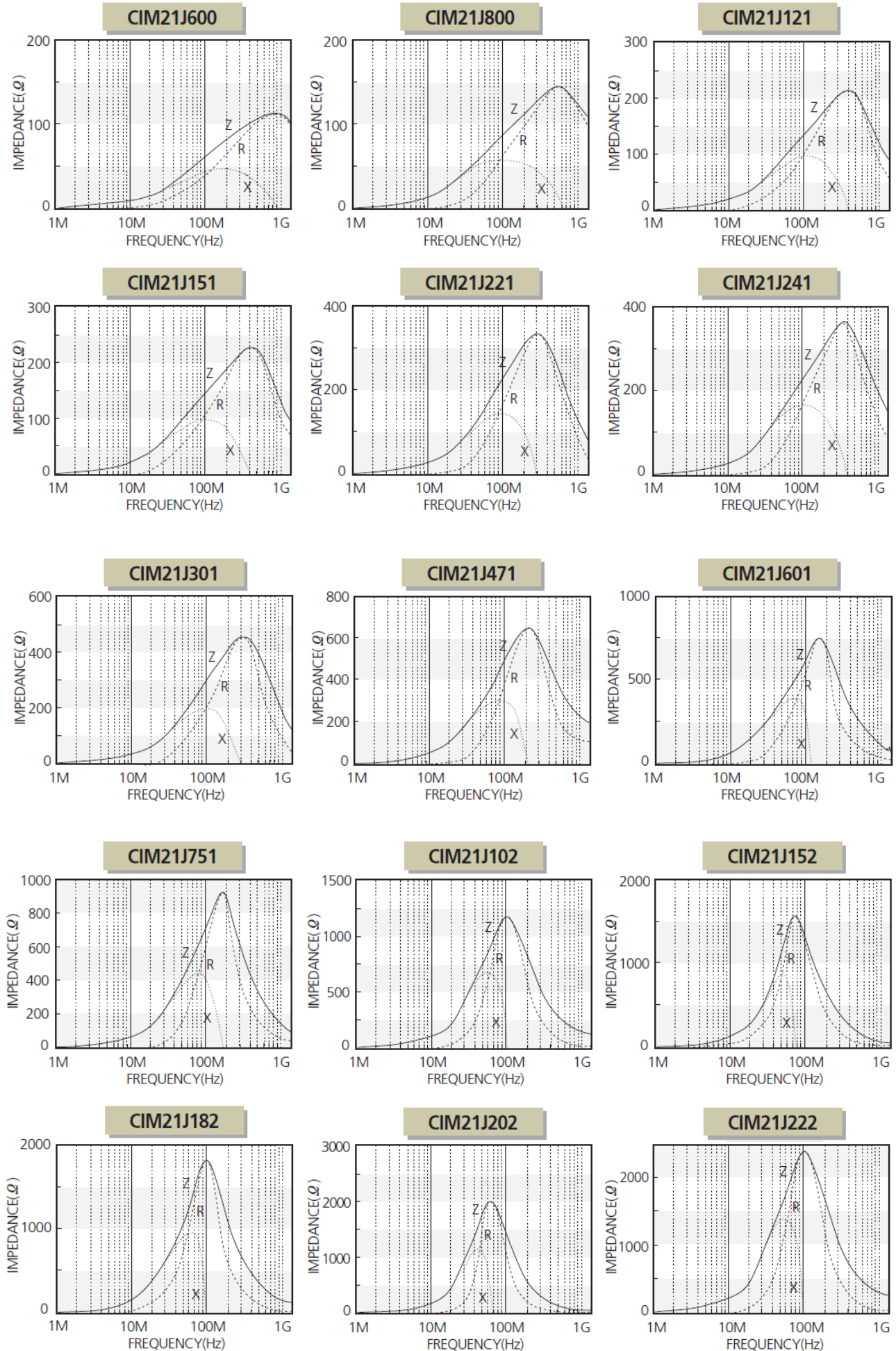


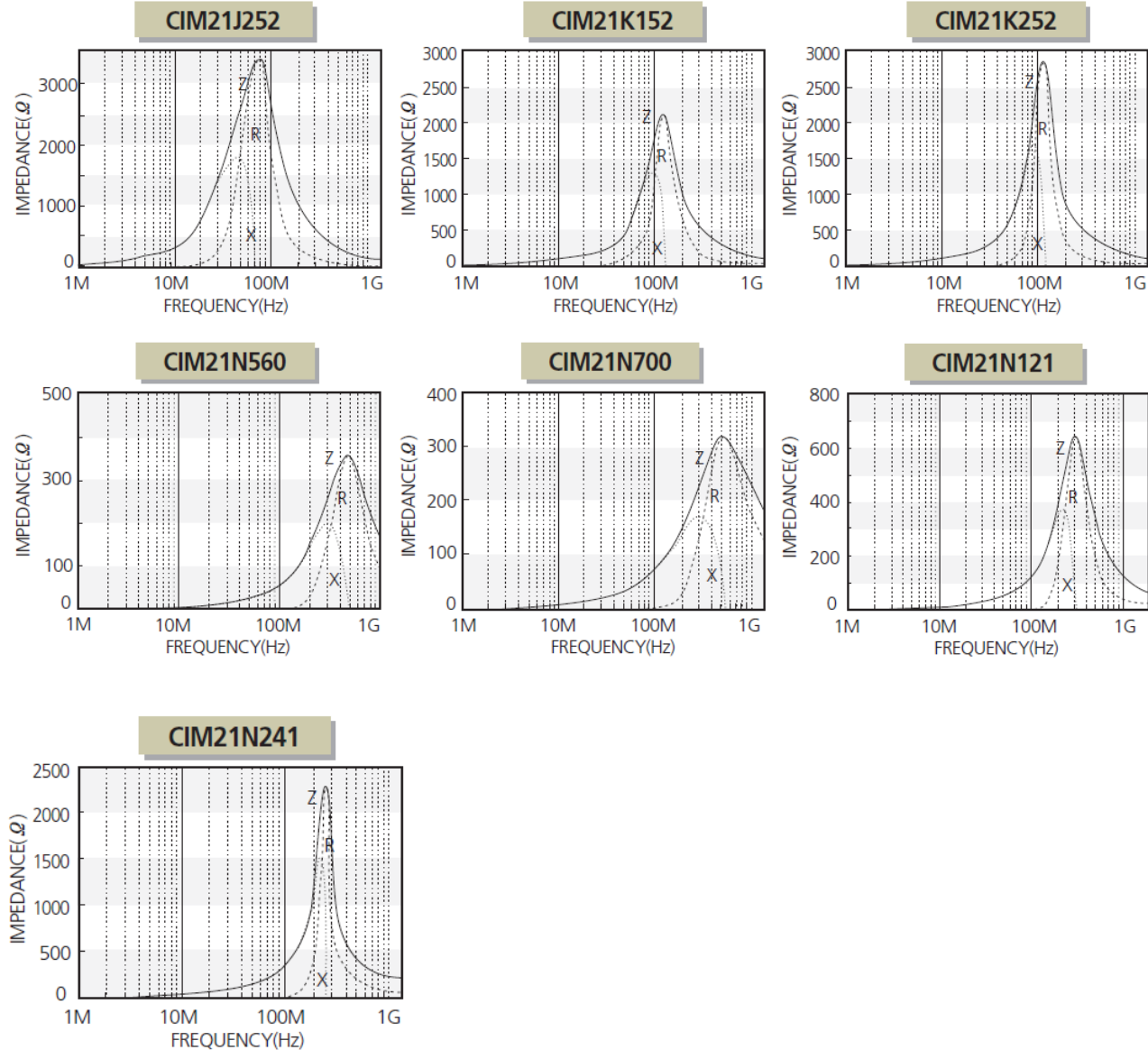
CIB21J300



CIB21J400







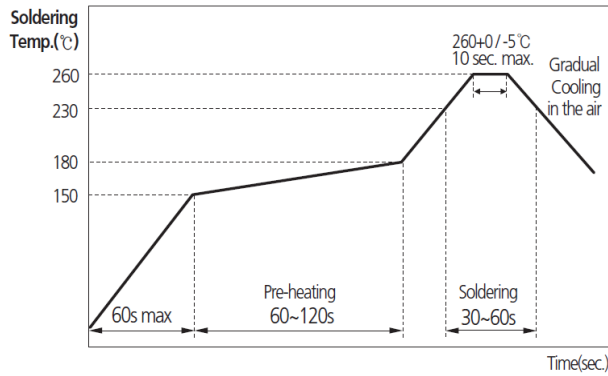
PRODUCT IDENTIFICATION

CI	M	21	U	121	N	E
(1)	(2)	(3)	(4)	(5)	(6)	(7)

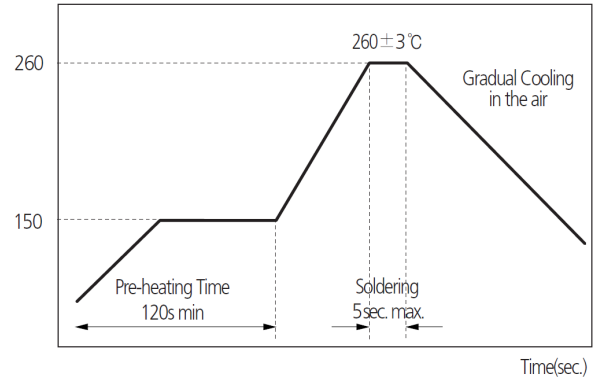
- (1) Chip Beads
- (2) M: Multi-layer type B: Mono-layer type
- (3) Dimension
- (4) Material Code
- (5) Nominal impedance (800:80Ω, 121:120Ω)
- (6) Thickness option(N:Standard, A:Thinner than standard, B:Thicker than standard)
- (7) Packaging(C:paper tape, E:embossed tape)

RECOMMENDED SOLDERING CONDITION

REFLOW SOLDERING



FLOW SOLDERING



PACKAGING

Packaging Style	Quantity(pcs/reel)
Embossed Taping	4,000



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The data sheets include the typical data for design reference only. If there is any question regarding the data sheets, please contact our sales personnel or application engineers.